Materials Declaration Form

IPC **Form Type ***	1752 Distribute	**Version**	2
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D **** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2023-12-05
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	**Representative Title**	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Signature Not
Verified

Digitally signed by
MDF Champion
Date: 2023.05.12
17:23:04 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
ST25R3919B-AQET	JSMG*TT3919D	A	998Z	2023-12-05
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	49.38	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	5X5X0.55	32	L Bend	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-10 Jun 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**TRUE**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**JSMG*TT3919D**				5999999.0	1000000.0
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	9.544	mg	supplier	die	Silicon (Si)	7440-21-3		3.680	mg	385583	74519
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	2305	445
				supplier	metallization	Copper (Cu)	7440-50-8		0.109	mg	11421	2207
				supplier	metallization	Titanium (Ti)	7440-32-6		4.631	mg	485226	93776
				supplier	metallization	Tungsten (W)	7440-33-7		1.029	mg	107816	20837
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	2200	425
				supplier	Passivation	Silicon Oxide	7631-86-9		0.052	mg	5448	1053
Glue Epoxy_EN4900GC_SD	M-011 Other inorganic materials	0.535	mg	Supplier	Organic Compounds	Acrylic resin	Proprietary		0.037	mg	70000	759
				Supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.011	mg	20000	217
				Supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.008	mg	15000	163
				Supplier	Organic Compounds	Acrylate	Proprietary		0.029	mg	54000	586
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.016	mg	30000	325
				Supplier	Organic Compounds	Peroxide	Proprietary		0.004	mg	8000	87
				Supplier	Organic Compounds	Additive	Proprietary		0.010	mg	18000	195
				Supplier	Metals	Silver	7440-22-4		0.420	mg	785000	8512
Mold Compound_ EME-G770(_Sumit	M-011 Other inorganic materials	9.158	mg	Supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.315	mg	21000	6388
				Supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.315	mg	21000	6388
				Supplier	Organic Compounds	Phenol Resin A	Proprietary		0.315	mg	21000	6388
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		5.860	mg	780450	118667
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		1.732	mg	115320	35079
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.094	mg	6230	1895
				Supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.210	mg	14000	4259
				Supplier	Organic Compounds	Phenol Resin B	Proprietary		0.315	mg	21000	6388
GOLD WIRE AU 3N TYPE_MKE	Bonding Wire	0.227	mg	Supplier	Metals	Gold	7440-57-5		0.227	mg	1000000	4596
Plating anode_Pure Tin_ASAHI	M-011 Other inorganic materials	0.719	mg	Supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14558
Leadframe _C7025+AG_HDS	Copper & its alloys	29.200	mg	Supplier	Metals	Copper	7440-50-8		26.780	mg	917140	542294
				Supplier	Metals	Nickel	7440-02-0		0.657	mg	22500	13304
				Supplier	Metals	Silicon	7440-21-3		0.076	mg	2600	1537
				Supplier	Metals	Magnesium	7439-95-4		0.034	mg	1150	680
				Supplier	Metals	Siliver	7440-22-4		1.653	mg	56610	33473